

N-Channel Enhancement Mode MOSFET

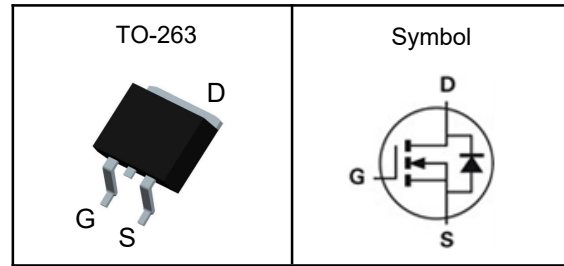
Features

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant
- 100% UIS and Rg Tested

Applications

- Power Management in Desktop Computer
- DC/DC Converters

Pin Description



V_{DSS}	150	V
$R_{DS(ON)-Typ}$	5	m Ω
I_D	135	A

Absolute Maximum Ratings ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter		N-Channel	Unit
V_{DSS}	Drain-Source Voltage		150	V
V_{GSS}	Gate-Source Voltage		± 20	V
T_J	Maximum Junction Temperature		-55 to 175	$^\circ\text{C}$
T_{STG}	Storage Temperature Range		-55 to 175	$^\circ\text{C}$
$I_{DM}^{①}$	Pulse Drain Current Tested	$T_C=25^\circ\text{C}$	530	A
I_D	Continuous Drain Current	$T_C=25^\circ\text{C}$	135	A
P_D	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	375	W
$I_{AS}^{②}$	Avalanche Current, Single pulse	$L=0.5\text{mH}$	60	A
$E_{AS}^{②}$	Avalanche Energy, Single pulse	$L=0.5\text{mH}$	540	mJ

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}^{③}$	Thermal Resistance-Junction to Ambient	55	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance-Junction to Case	0.34	$^\circ\text{C}/\text{W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C .

Note ③ : Surface Mounted on 1in^2 FR-4 board with 1oz.



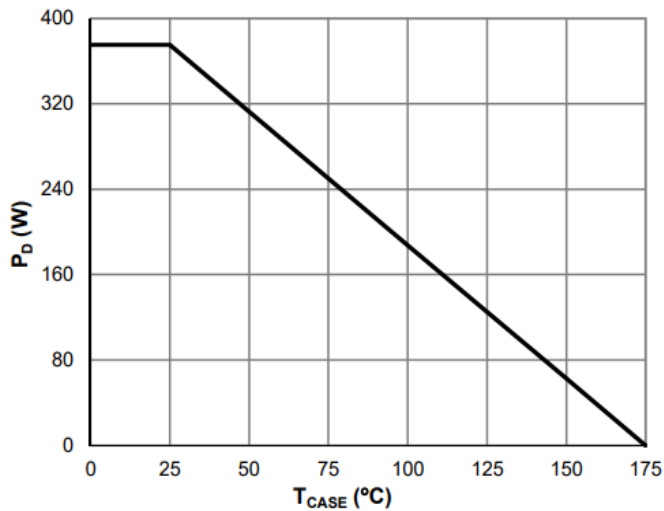
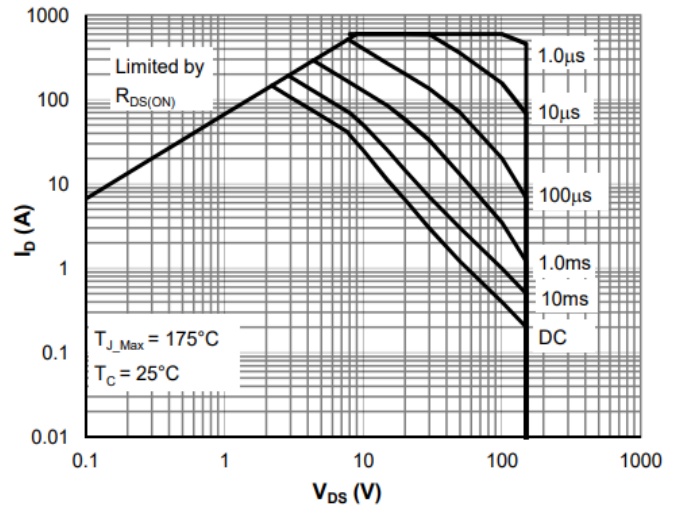
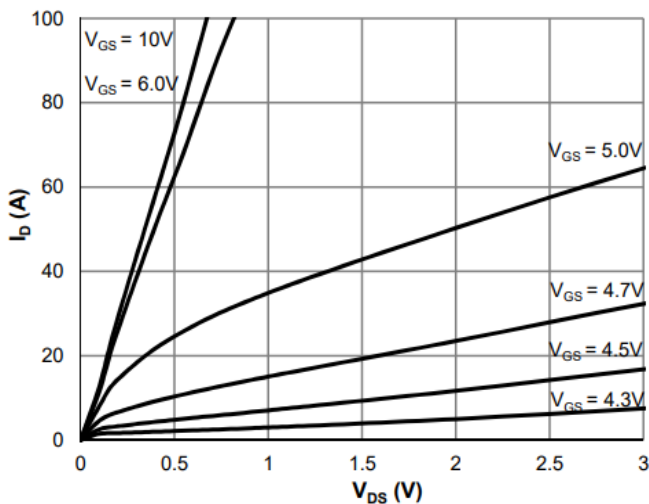
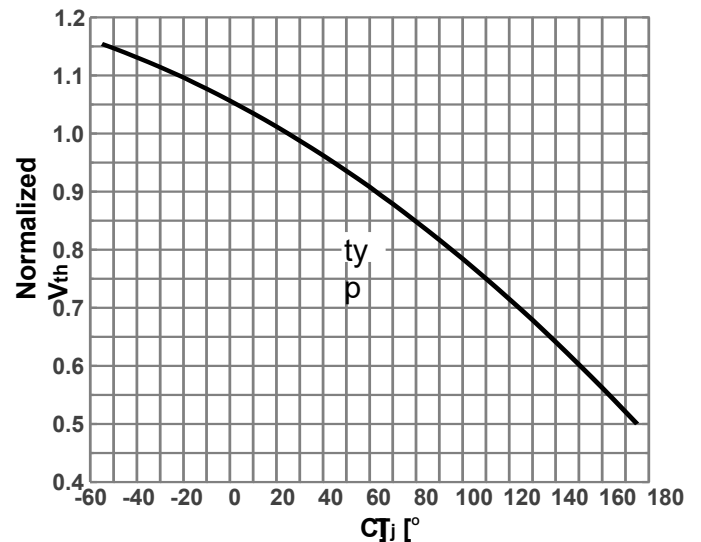
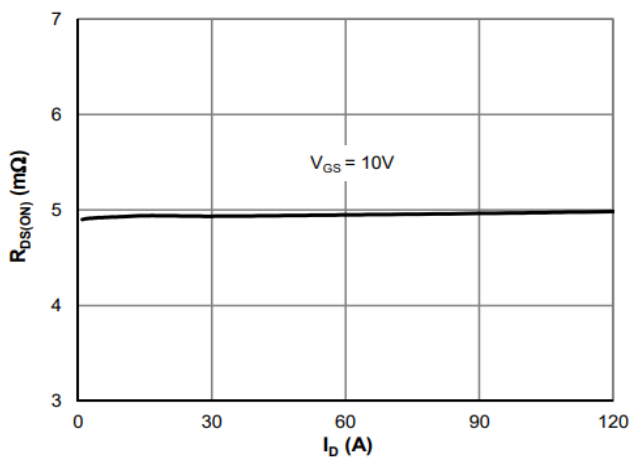
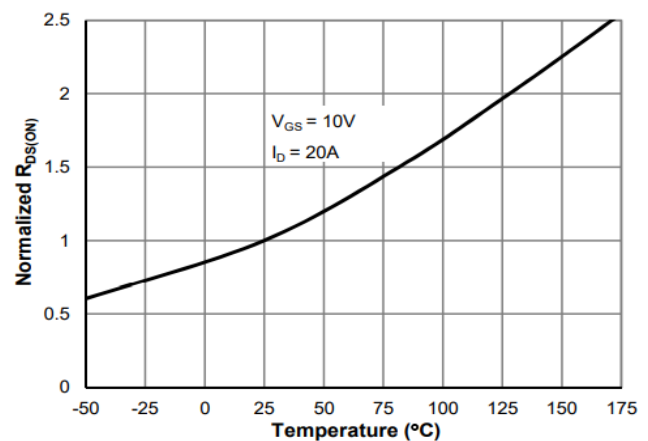
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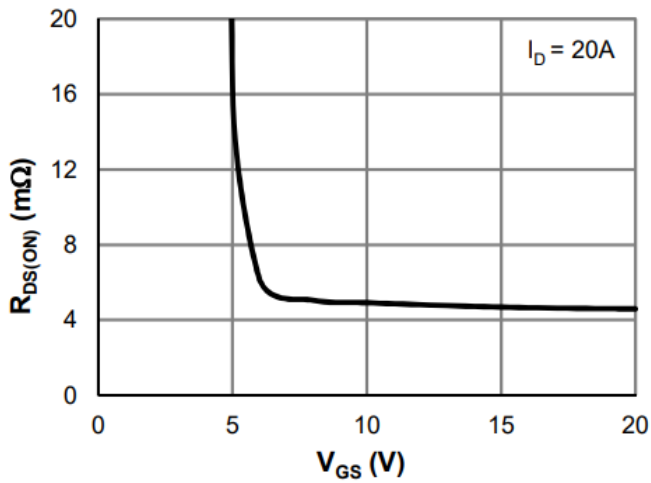
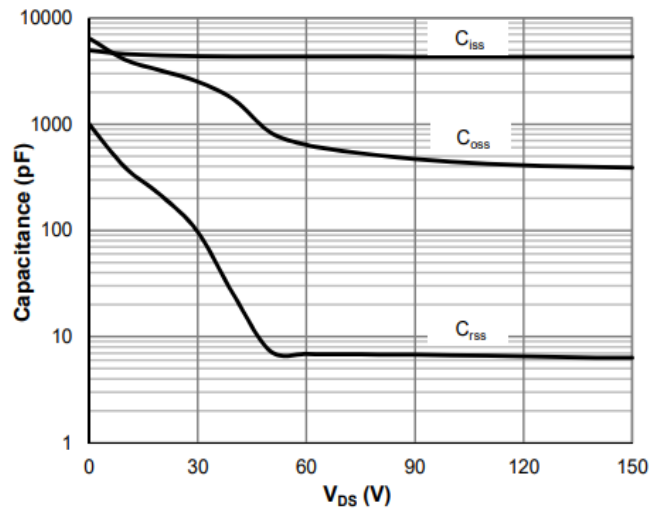
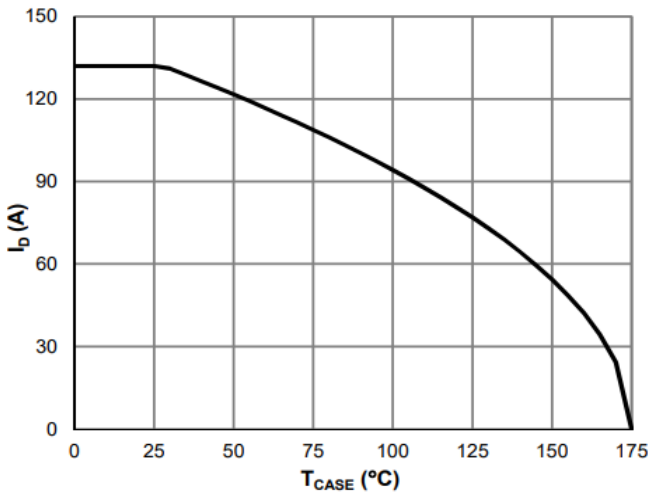
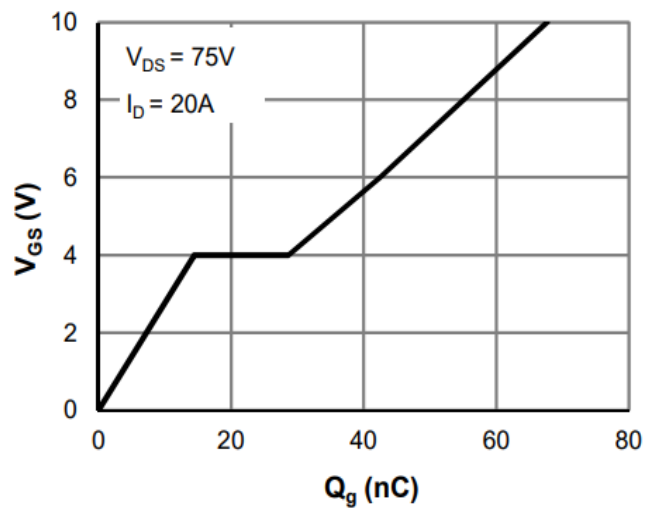
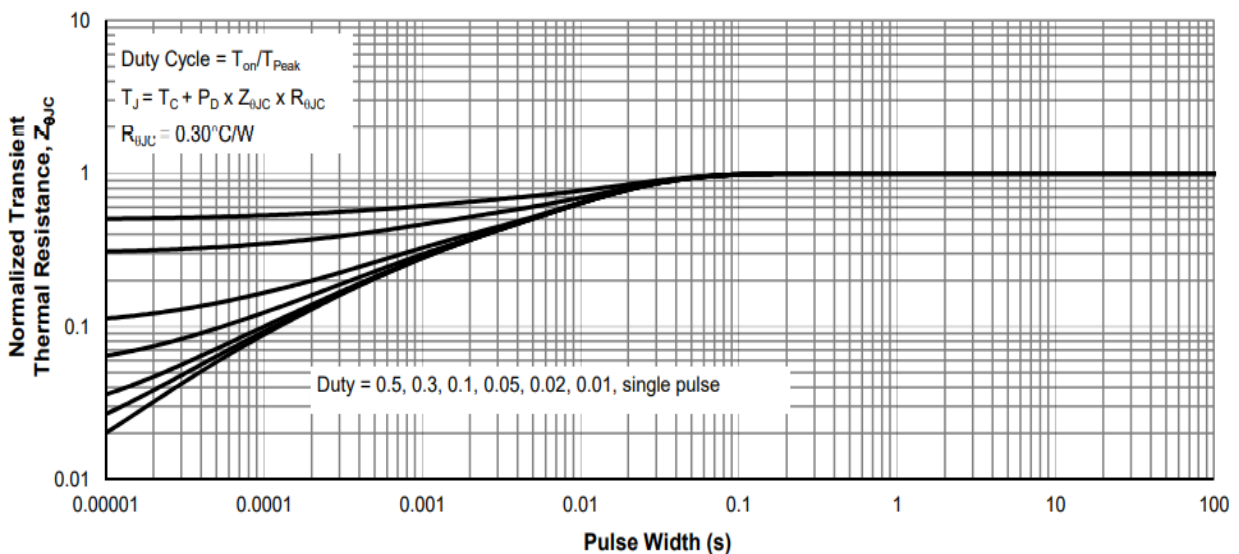
Electrical Characteristics ($T_J=25^{\circ}\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	150	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=150V, V_{GS}=0V$	---	---	1	μA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2	3	4	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
$R_{DS(on)}$	Drain-Source On-state Resistance	$V_{GS}=10V, I_D=20A$	---	5	6.2	m Ω
Dynamic Characteristics^⑤						
C_{iss}	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=75V,$ Freq.=1MHz	---	4300	---	pF
C_{oss}	Output Capacitance		---	530	---	
C_{riss}	Reverse Transfer Capacitance		---	7	---	
$T_{d(on)}$	Turn-on Delay Time	$V_{GS}=10V, V_{DD}=75V,$ $I_D=20A, R_G=6\Omega$	---	19	---	nS
T_r	Turn-on Rise Time		---	30	---	
$T_{d(off)}$	Turn-off Delay Time		---	53	---	
T_f	Turn-off Fall Time		---	40	---	
Q_g	Total Gate Charge	$V_{GS}=10V, V_{DD}=75V,$ $I_D=20A$	---	68	---	nC
Q_{gs}	Gate-Source Charge		---	15	---	
Q_{gd}	Gate-Drain Charge		---	14	---	
Source-Drain Characteristics						
$V_{SD}^{④}$	Diode Forward Voltage	$I_S=15A, V_{GS}=0V$	---	---	1.2	V
t_{rr}	Reverse Recovery Time	$I_F=15A, V_R=75V$ $di_F/dt=100A/\mu s$	---	100	---	nS
Q_{rr}	Reverse Recovery Charge		---	150	---	nC

Note ④: Pulse test (pulse width \leq 300 μs , duty cycle \leq 2%).

Note ⑤: Guaranteed by design, not subject to production testing.

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Typical Characteristics

Diagram 1: Power dissipation

Diagram 2: Max. Safe Operating Area

Diagram 3: Typ. output characteristics

Diagram 4: Gate threshold voltage vs. Junction temperature

Diagram 5: On-state resistance vs. Drain current

Diagram 6: On-state resistance vs. Junction temperature

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Diagram 7: On-state resistance vs. Vgs characteristics

Diagram 8: Typ. capacitances

Diagram 9: Maximum Drain Current

Diagram 10: Typ. gate charge

Diagram 11: Normalized Maximum Transient Thermal Impedance

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TO-263 Package Outline Data
